

100V P-Channel Enhancement Mode MOSFET**Description**

The PECN16P10G uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

- ◆ $V_{DS} = -100V$ $I_D = -16A$
 $R_{DS(ON)}(\text{Typ.}) = 150\text{m}\Omega$ @ $V_{GS} = -10V$
 $R_{DS(ON)}(\text{Typ.}) = 200\text{m}\Omega$ @ $V_{GS} = -4.5V$
- ◆ High power and current handing capability
- ◆ Lead free product is acquired
- ◆ Surface mount package

Application

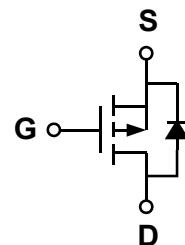
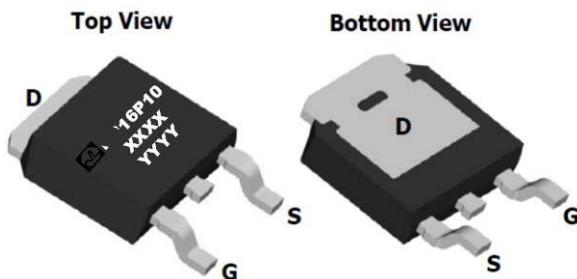
- ◆ Load switch

Package

- ◆ TO-252-2L

100% UIS TESTED!

100% ΔV_{ds} TESTED!

Schematic diagram**Marking and pin assignment**

PECN16P10—NP16P10G

XXXX—Date Code

YYYY—Quality Code.

**Ordering Information**

Part Number	Storage Temperature	Package	Devices Per Reel
PECN16P10 G	-55°C to +150°C	TO-252-2L	2500

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter	symbol	limit	unit
Drain-source voltage	V_{DS}	-100	V
Gate-source voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	-16	A
		-9.8	
Pulsed Drain Current	I_{DP}	-64	A
Avalanche Current	I_{AS}	-16	A
Avalanche energy(L=0.5mH)	E_{AS}	345	mJ
Maximum power dissipation	P_D	150	W
		100	
Operating junction Temperature range	T_j	-55—150	°C

Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =-250μA	-100	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =-100V, V _{GS} =0V	-	-	-25	μA
		V _{DS} =-80V, V _{GS} =0V, T _J =150°C	-	-	-100	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-1.5	-2.6	-3.2	V
Drain-source on-state resistance ¹	R _{DS(ON)}	V _{GS} =-10V, I _D =-16A	-	150	180	mΩ
		V _{GS} =-4.5V, I _D =-10A	-	200	250	
On Status Drain Current	I _{D(ON)}	V _{DS} =-50V, V _{GS} =-10V	-16	-	-	A
Diode Characteristics						
Diode Forward Voltage ¹	V _{SD}	I _{SD} =-16A, V _{GS} =0V	-	-0.8	-1.3	V
Diode Continuous Forward Current	I _S		-	-16	-	A
Reverse Recovery Time	t _{rr}	I _F =-16A, dI/dt=-100A/us	-	35	-	ns
Reverse Recovery Charge	Q _{rr}		-	46	-	nC
Dynamic Characteristics²						
Gate Resistance	R _G	V _{GS} =0V, V _{DS} =0V, f=1MHz	-	0.65	-	Ω
Input capacitance	C _{ISS}	V _{GS} =0V, V _{DS} =-25V f=1.0MHz	-	1180	-	pF
Output capacitance	C _{OSS}		-	250	-	
Reverse transfer capacitance	C _{RSS}		-	75	-	
Turn-on delay time	t _{D(ON)}	V _{GS} =-10V, V _{DD} =-50V, R _D =2.4Ω, I _D =-16A, R _G =9.1Ω	-	11	-	ns
Turn-on Rise time	t _r		-	25	-	
Turn-off delay time	t _{D(OFF)}		-	56	-	
Turn-off Fall time	t _f		-	36	-	
Total gate charge	Q _g	V _{GS} =-10V, I _D =-16A V _{DS} =-80V	-	37	-	nC
Gate-source charge	Q _{gs}		-	5	-	
Gate-drain charge	Q _{gd}		-	15	-	

Note: 1: Pulse test; pulse width ≤ 300ns, duty cycle ≤ 2%.

2: Guaranteed by design, not subject to production testing.

Thermal Characteristics

Parameter	Symbol	Typical	Unit
Thermal Resistance-Junction to Case	R _{θjc}	1.7	°C/W
Thermal Resistance junction-to ambient	R _{θja}	62.5	

Figure A: Gate Charge Test Circuit & Waveforms

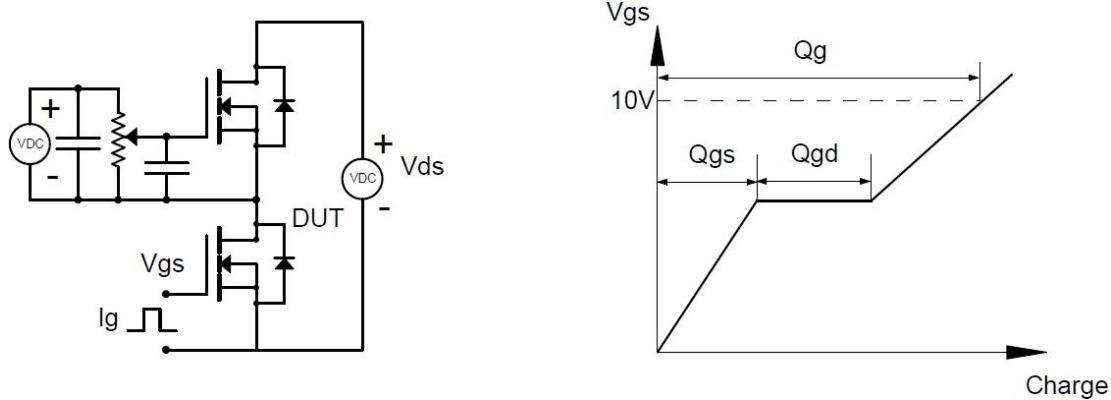


Figure B: Resistive Switching Test Circuit & Waveforms

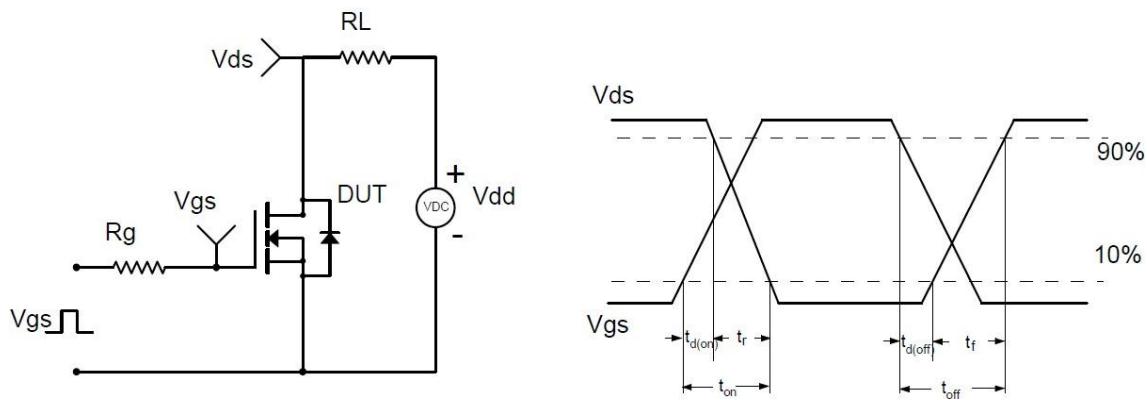


Figure C: Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

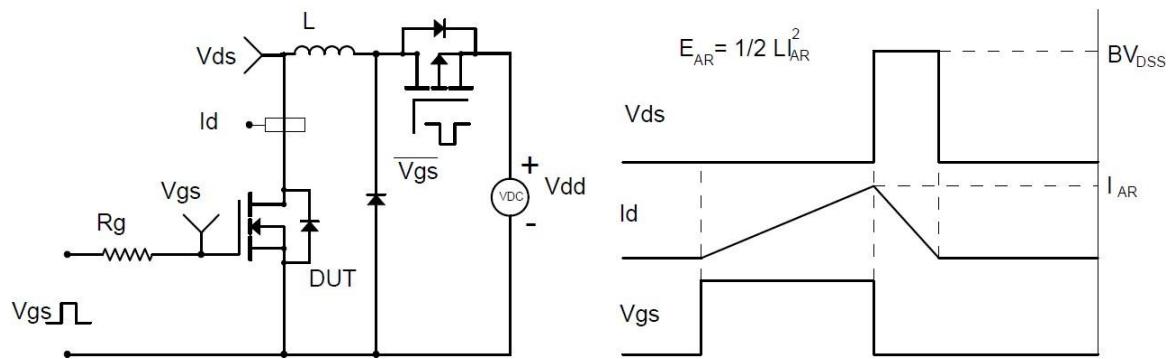
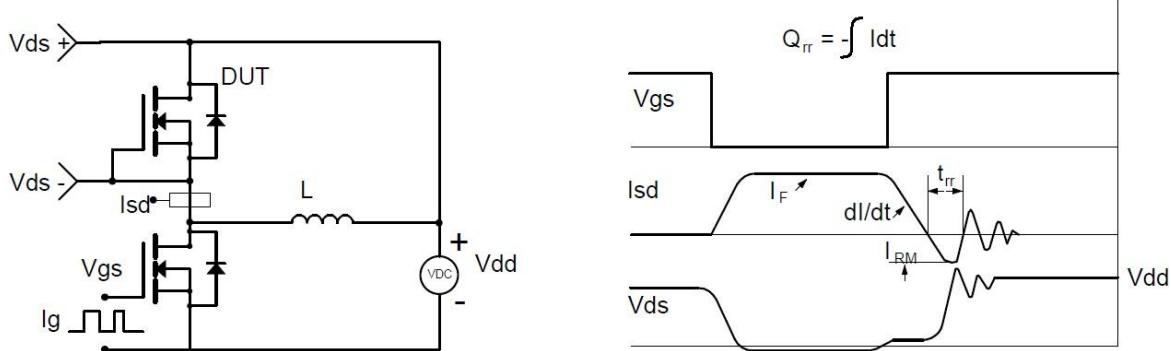
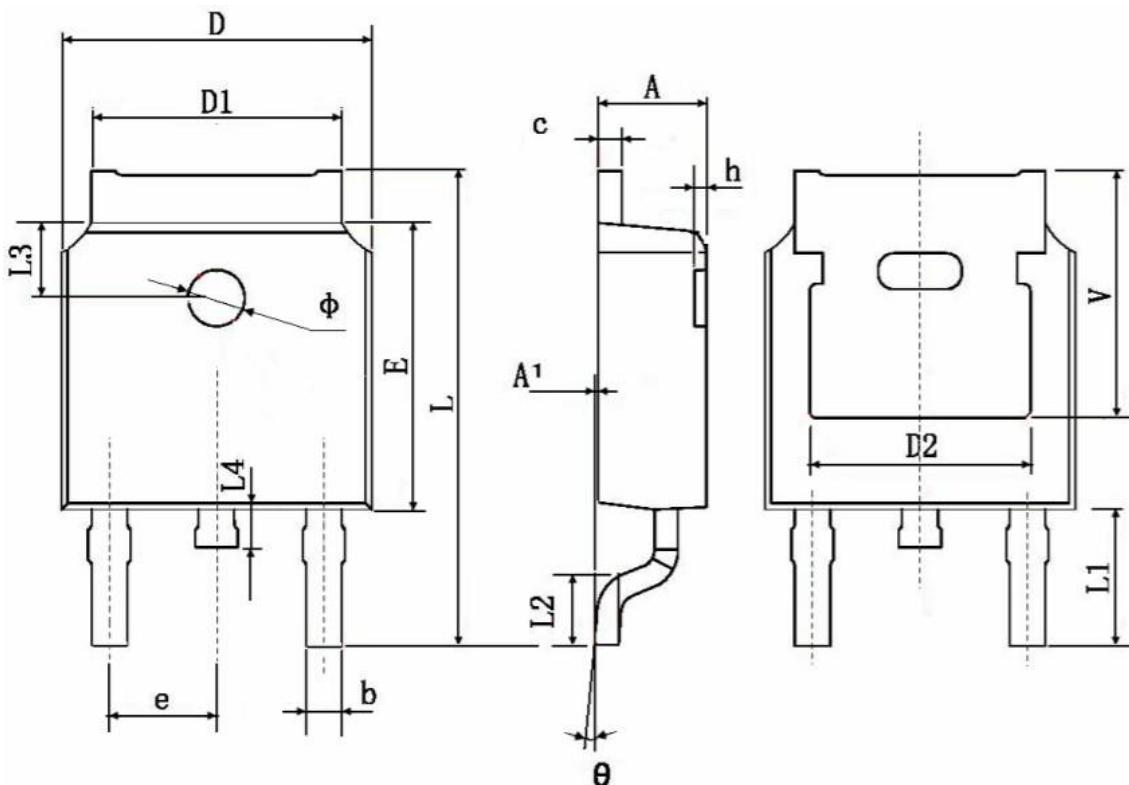


Figure D: Diode Recovery Test Circuit & Waveforms



Package Information

- TO-252-2L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	